

YorChip and Digitho announce UniPack Advanced Packaging

Low cost Advanced Packaging – eliminating interposers, bridges and substrates.

SAN RAMON, CA, UNITED STATES, August 12, 2026 /EINPresswire.com/ -- YorChip, Inc. and Digitho are pleased to announce its breakthrough 2.5D low-cost advanced UniPack Advanced Packaging solution is ready for early alpha customer trials. UniPack currently allows integration of any pad pitch from 200 microns to 35 microns

with a roadmap to sub-10-micron pitch in 2028 timeframe. Yole group has forecasted advanced packaging market to grow rapidly to exceed \$100Bn market by 2031. source:

<https://www.yolegroup.com/product/report/status-of-the-advanced-packaging-industry-2026>).

“

“The key focus of our joint development has been to eliminate expensive and hard to obtain interposers, bridges and substrates. We replace these with a dry PID (Photo Imageable Dielectric) .”

Richard Beaudry

YorChips’ CEO and founder, Kash Johal, said, “UniPack enables universal packaging and integration of standard and advanced chiplets and other semiconductor devices. Passives and IVR die can also be integrated seamlessly, and we are excited to engage with early customers to validate the technology. Our initial validation plan includes packaging multiple FPGA die in Q4 of this year.”

Digitho CEO and founder, Richard Beaudry, said, “The key focus of our joint development has been to eliminate expensive and hard to obtain interposers, bridges and substrates. We replace these with a dry PID (Photo

Imageable Dielectric) and build a complete heterogenous wafer of known good die. Currently we can support 35-micron pitch – but once our programmable photo mask becomes available, we expect to support below 10-micron pitch.

QuickLogic CEO, Brian Faith, said, “We are excited to see the launch of UniPack for integration of



wafer scale heterogenous devices which will enable leading edge SWAP (Size, Weight, Area and Power) solutions, all of which are critical for our target markets. We look forward to evaluating UniPack for our forthcoming high-density FPGA-based silicon solutions.”

Availability

UniPack is available for early customer validation, and we anticipate broad availability by mid 2027.

About YorChip

We are a Silicon Valley startup with patent pending technology for programmable Chiplet PHY technology. We offer intellectual property licensing and plan to offer Chiplets for re-sale to end customers across a broad range of markets leveraging our PHY and advanced packaging technology.

About Digitho

We are a Canada based start-up with patented technology of dynamic reprogrammable photomasks. Direct-write capability using existing photolithography system without modification. This opens innovations to personalize devices individually and enable next generation chip-to-chip interconnect with adjusting link for die alignment errors.

kash johal

YorChip Inc.

+1 408-390-8649

[email us here](#)

This press release can be viewed online at: <https://www.einpresswire.com/article/933414195>

EIN Presswire's priority is source transparency. We do not allow opaque clients, and our editors try to be careful about weeding out false and misleading content. As a user, if you see something we have missed, please do bring it to our attention. Your help is welcome. EIN Presswire, Everyone's Internet News Presswire™, tries to define some of the boundaries that are reasonable in today's world. Please see our Editorial Guidelines for more information.

© 1995-2026 Newsmatics Inc. All Right Reserved.